HFM301 THRU HFM307

List

List.. 1

Package outline.. 2

Features.. 2

Mechanical data.. 2

Maximum ratings 2

Rating and characteristic curves.. 3

Pinning information..4

Marking.. 4

Suggested solder pad layout.. 4

Packing information..5

Reel packing.. 6

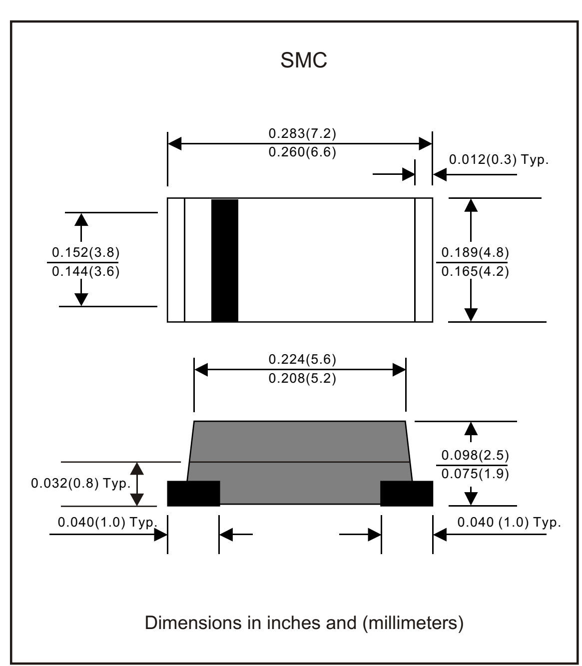
Suggested thermal profiles for soldering processes..6

High reliability test capabilities..7

HFM301 THRU HFM307

3.0A Surface Mount High Effciency Rectifiers-50-1000V

Package outline



Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- High current capability.
- Ultrafast recovery time for high efficiency.
- High surge current capability.
- Glass passivated chip junction.
- Lead-free parts meet RoHS requirments.

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AB / SMC
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.19 gram

Maximum ratings (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	Ambient temperature = 55°C	I_O			3.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I_{FSM}			100	A
Reverse current	V_R = V_{RRM} T_A = 25°C	I_R			10.0	uA
	V_R = V_{RRM} T_A = 100°C				300	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		15		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		70		pF
Storage temperature		T_{STG}	-65		+175	°C

SYMBOLS	V_{RRM} *1 (V)	V_{RMS} *2 (V)	V_R *3 (V)	V_F *4 (V)	T_{RR} *5 (nS)	Operating temperature T_J, (°C)
HFM301	50	35	50	1.00	50	-55 to +150
HFM302	100	70	100			
HFM303	200	140	200			
HFM304	400	280	400	1.30		
HFM305	600	420	600	1.70	75	
HFM306	800	560	800			
HFM307	1000	700	1000			

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage

*5 Reverse recovery time

Rating and characteristic curves (HFM301 THRU HFM307)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

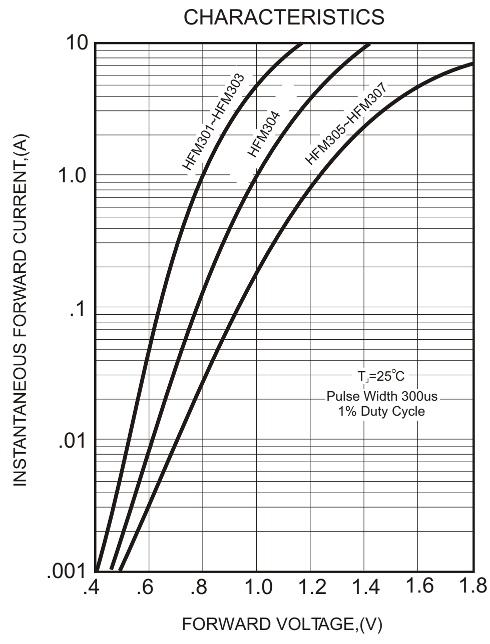


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

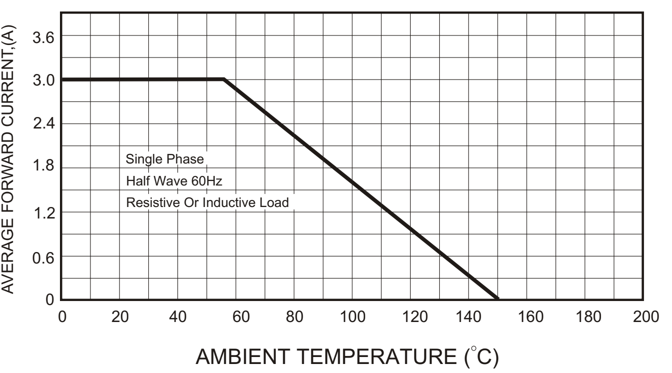
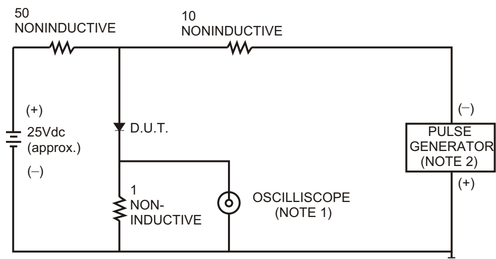


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

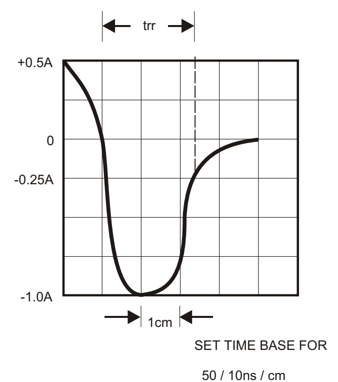


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

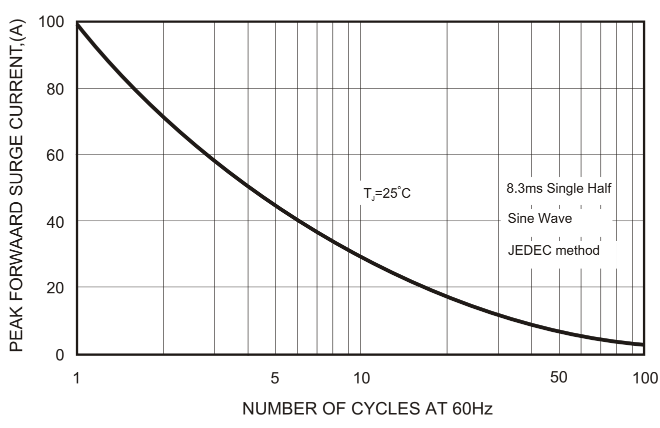
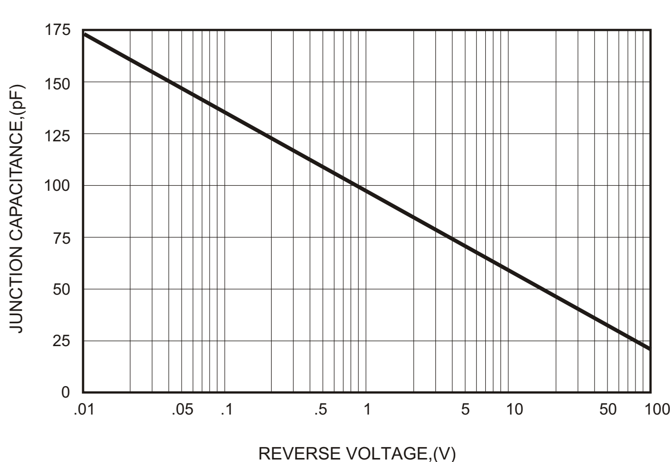


FIG.5-TYPICAL JUNCTION CAPACITANCE



HFM301 THRU HFM307

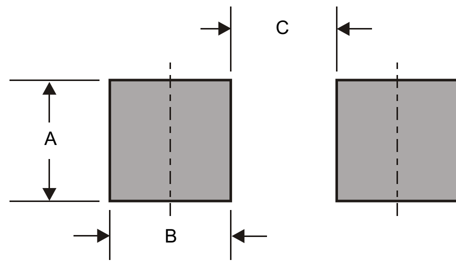
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode	1 2	1 2

Marking

Type number	Marking code
HFM301	H31
HFM302	H32
HFM303	H33
HFM304	H34
HFM305	H35
HFM306	H36
HFM307	H37

Suggested solder pad layout

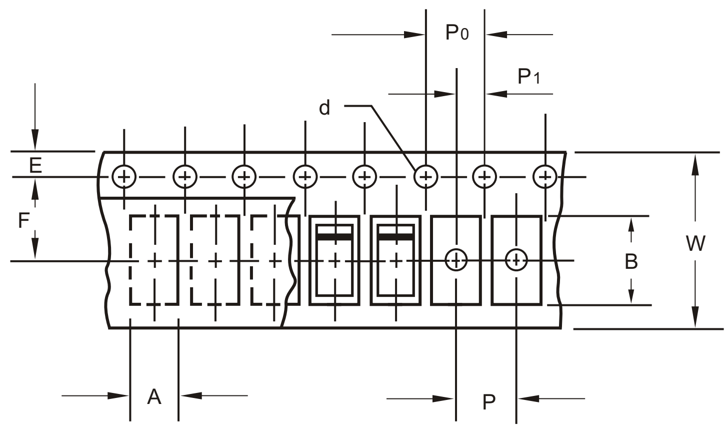


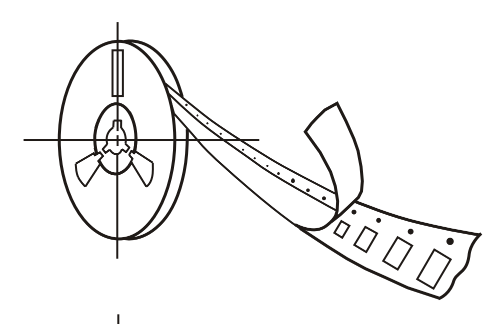
Dimensions in inches and (millimeters)

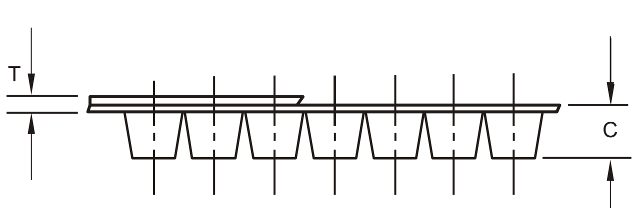
PACKAGE	A	B	C
SMC	0.189 (4.80)	0.063 (1.60)	0.181 (4.60)

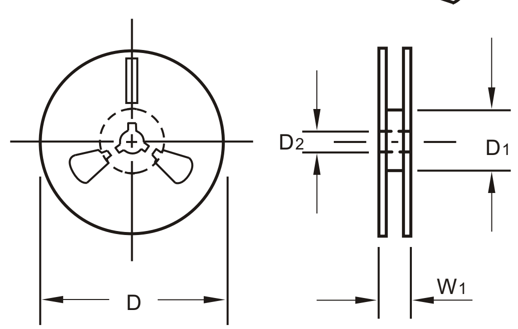
HFM301 THRU HFM307

Packing information









unit:mm

Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	5.10
Carrier length	B	0.1	7.20
Carrier depth	C	0.1	2.50
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D_1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D_1	min	62.00
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	12.00
Reel width	W_1	1.0	18.00

Note:Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

HFM301 THRU HFM307

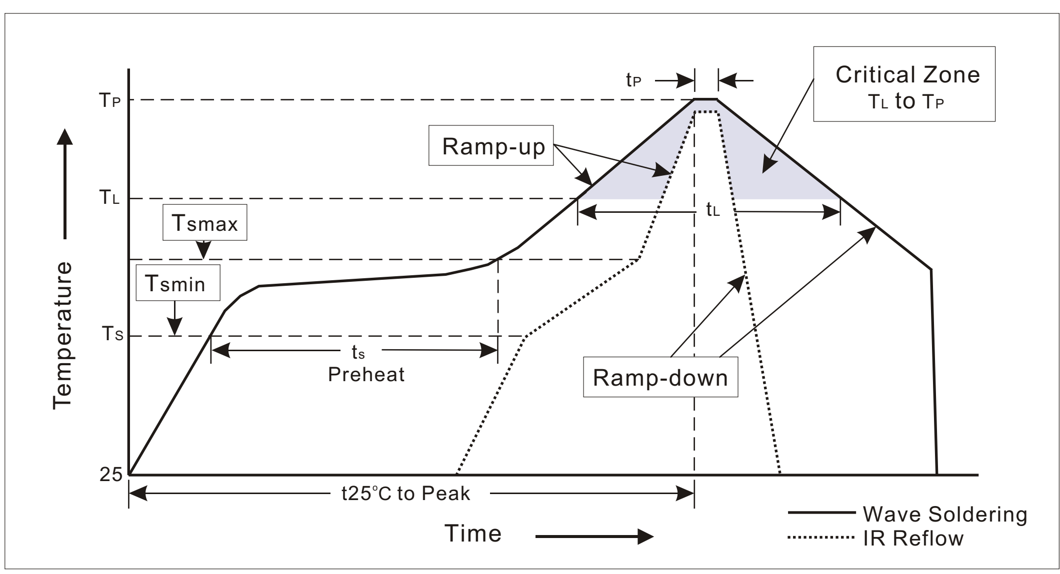
Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3000	8.0	6000	337*337*37	330	360*340*370	48,000	17.2

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=10°C~35°C Humidity=65%±15%

2.Reflow soldering of surface-mount devices



3.Flow (wave)soldering (solder dipping)

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(t_s)	100°C 150°C 60~120sec
Tsmax to T_L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	183°C 60~150sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

HFM301 THRU HFM307

High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec. immerse body into solder 1/16"±1/32"	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	V_R=80% rate at T_A=150°C for 168 hrs.	MIL-STD-750D METHOD-1026
4. Forward Operation Life	Rated average rectifier current at T=25°C for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	T_A = 25°C, I_F = I_O On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	15P_{SIG} at T_A=121°C for 4 hrs.	
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
9. Forward Surge	8.3ms single half sine-wave superimposed on rated load, one surge.	MIL-STD-750D METHOD-4066-2
10. Humidity	at T_A=65°C, RH=98% for 1000hrs.	MIL-STD-750D METHOD-1038
11. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031
12. Solvent Resistance	Dip into Freon at 25°C for 1 min.	MIL-STD-202F METHOD-215